

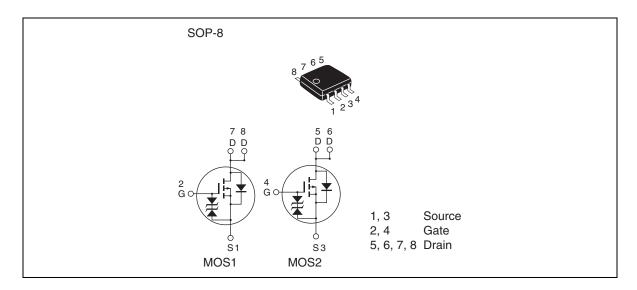
# Silicon P Channel Power MOS FET High Speed Power Switching

REJ03G0067-0100Z Rev.1.00 Aug.29.2003

# **Features**

- Low on-resistance
- Capable of 4.5 V gate drive
- High density mounting
- "J" is for Automotive application High temperature D-S leakage guarantee Avalanche rating

### **Outline**



# **Absolute Maximum Ratings**

 $(Ta = 25^{\circ}C)$ 

Item	Symbol	Ratings	Unit	
		HAT1055R	HAT1055RJ	_
Drain to source voltage	V <sub>DSS</sub>	-60	-60	V
Gate to source voltage	V <sub>GSS</sub>	±20	±20	V
Drain current	I <sub>D</sub>	<b>-</b> 5	<b>-</b> 5	A
Drain peak current	I <sub>D</sub> (pulse) <sup>Note1</sup>	-40	-40	A
Avalanche current	I <sub>AP</sub> Note4	_	<b>-</b> 5	A
Avalanche energy	E <sub>AR</sub> Note4	_	2.14	mJ
Channel dissipation	Pch <sup>Note2</sup>	2	2	W
Channel dissipation	Pch <sup>Note3</sup>	3	3	W
Channel temperature	Tch	150	150	°C
Storage temperature	Tstg	-55 to +150	-55 to +150	°C

Notes: 1. PW  $\leq$  10 $\mu$ s, duty cycle  $\leq$  1%

- 2. 1 Drive operation: When using the glass epoxy board (FR4 40 x 40 x 1.6 mm), PW  $\leq$  10 s
- 3. 2 Drive operation: When using the glass epoxy board (FR4 40 x 40 x 1.6 mm), PW  $\leq$  10 s
- 4. Value at Tch = 25°C, Rg  $\geq$  50  $\Omega$

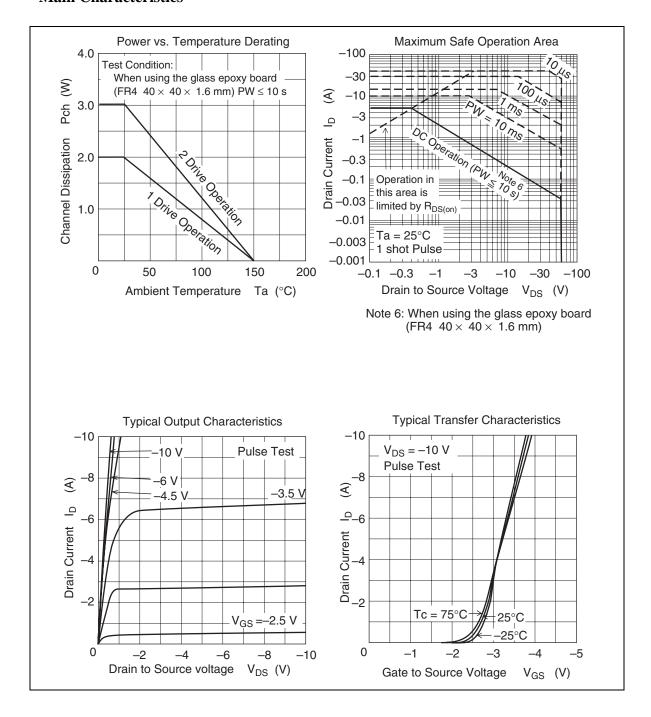
# **Electrical Characteristics**

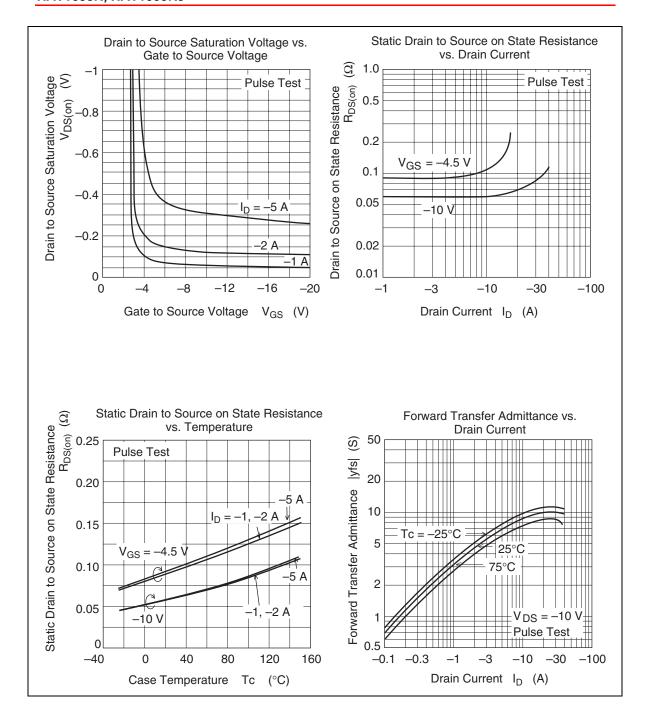
 $(Ta = 25^{\circ}C)$ 

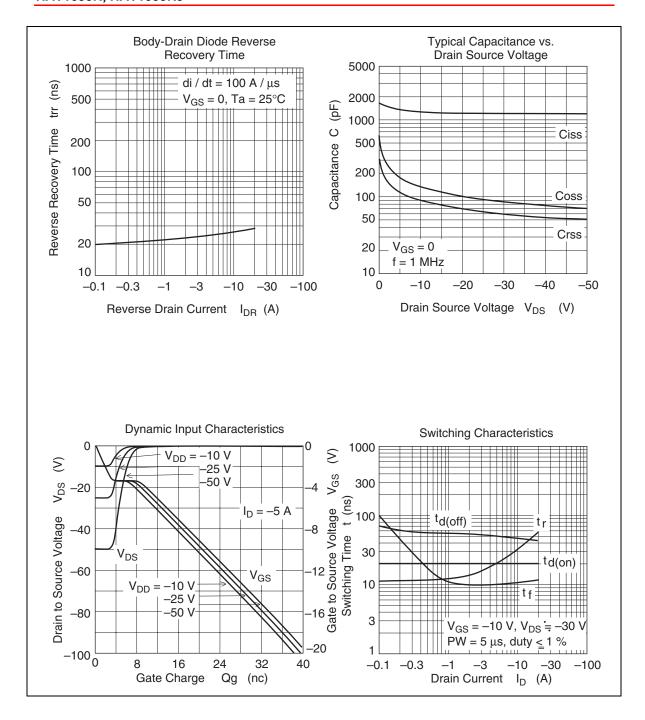
Item		Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage		$V_{(BR)DSS}$	-60	_	_	V	$I_D = -10 \text{ mA}, V_{GS} = 0$
Gate to Source breakdown voltage		V <sub>(BR)GSS</sub>	±20	_	_	V	$I_G = \pm 100 \ \mu A, \ V_{DS} = 0$
Zero gate voltage dra	ain current	I <sub>DSS</sub>	_	_	-1	μΑ	$V_{DS} = -60 \text{ V}, V_{GS} = 0$
Zero gate voltage	HAT1055R	I <sub>DSS</sub>	_	_	_	μΑ	$V_{DS} = -48 \text{ V}, V_{GS} = 0$
drain current	HAT1055RJ	I <sub>DSS</sub>	_	_	-10	μΑ	 Ta = 125°C
Gate to source leak current		I <sub>GSS</sub>	_	_	±10	μΑ	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0$
Gate to source cutof	f voltage	V <sub>GS(off)</sub>	-1.0	_	-2.5	V	$V_{DS} = -10 \text{ V}, I_{D} = -1 \text{ mA}$
Forward transfer adr	nittance	y <sub>fs</sub>	3	5	_	S	$I_D = -2.5 \text{ A}^{\text{Note5}}, V_{DS} = -10 \text{ V}$
Static drain to source	on state	R <sub>DS(on)</sub>	_	60	76	mΩ	$I_D = -2.5 \text{ A}^{\text{Note5}}, V_{GS} = -10 \text{ V}$
resistance		R <sub>DS(on)</sub>	_	90	130	mΩ	$I_D = -2.5 \text{ A}^{\text{Note5}}, V_{GS} = -4.5 \text{ V}$
Input capacitance		Ciss	_	1350	_	pF	$V_{DS} = -10 \text{ V}, V_{GS} = 0$
Output capacitance		Coss	_	135	_	pF	f = 1 MHz
Reverse transfer capacitance		Crss	_	85	_	pF	_
Total gate charge		Qg	_	21	_	nC	V <sub>DD</sub> = -25 V
Gate to source charge		Qgs	_	3	_	nC	$V_{GS} = -10 \text{ V}$
Gate to drain charge		Qgd	_	4	_	nC	$I_D = -5 A$
Turn-on delay time		td(on)	_	20	_	ns	$V_{GS} = -10 \text{ V}, I_{D} = -2.5 \text{ A}$
Rise time		tr	_	15	_	ns	V <sub>DD</sub> ≅ −30 V
Turn-off delay time		td(off)	_	55	_	ns	$R_L = 12 \Omega$
Fall time		tf	_	10	_	ns	$R_G = 4.7 \Omega$
Body-drain diode forward voltage		$V_{DF}$	_	-0.85	-1.10	V	$I_F = -5 \text{ A}, V_{GS} = 0^{\text{Note5}}$
Body-drain diode reverse recovery time		trr	_	25	_	ns	$I_F = -5 \text{ A}, V_{GS} = 0$ diF/dt = 100 A/µs

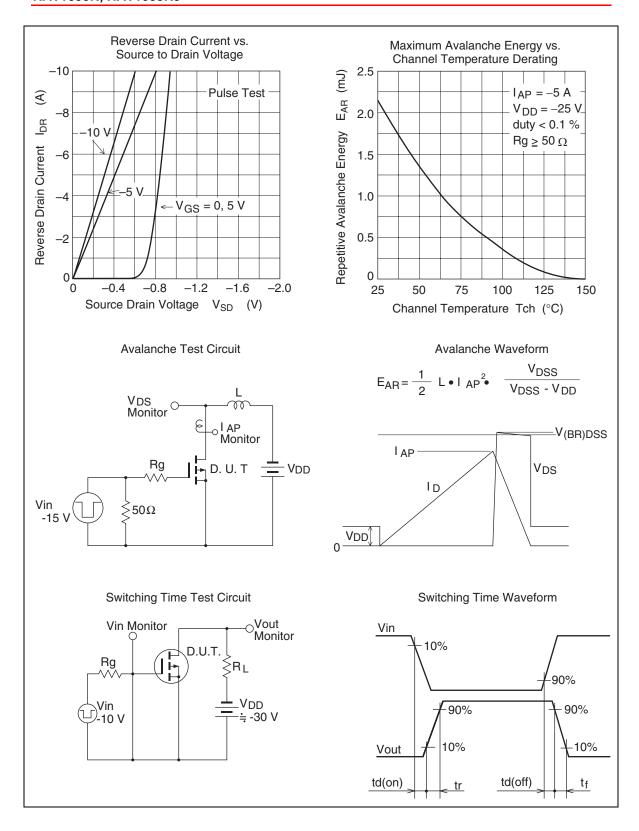
Notes: 5. Pulse test

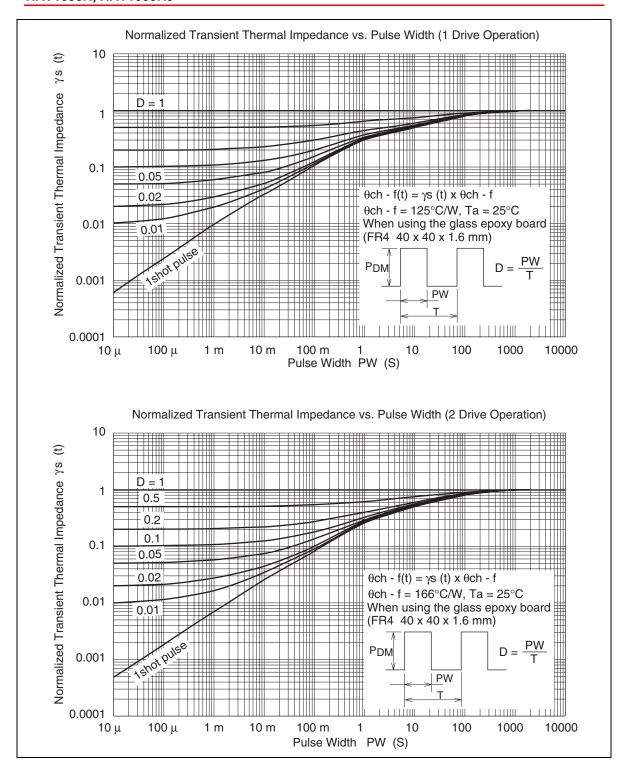
#### **Main Characteristics**



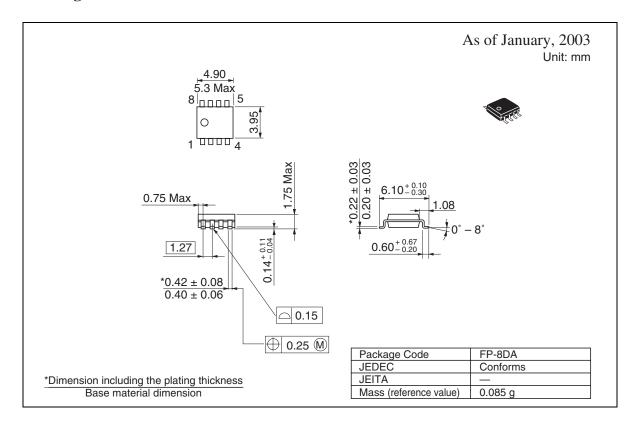








# **Package Dimensions**



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